MPI2520

High Current, Low Profile, Miniature Power Inductors

Product description:

- Halogen free, lead free, RoHS compliant
- 125°C maximum total temperature operation
- 2.7 x 2.2 x 1.0 / 1.2mm maximum surface mount package
- Magnetically shielded, low EMI
- Inductance range from 0.47µH to 10.0µH
- Current range from 1.1 to 4.8 amps

Applications:

- Mobile/smart phones
- Handheld/mobile equipment
- Digital cameras
- Media players
- GPS
- MP3 Players
- Tablets/eReaders

Environmental data:

- Storage temperature range (Component): -40°C to +125°C
- Operating temperature range: -40°C to +125°C (ambient + self temperature rise)
- Solder reflow temperature: J-STD-020D compliant

Packaging:

- Supplied in tape and reel packaging, 3000 parts per 7" diameter reel

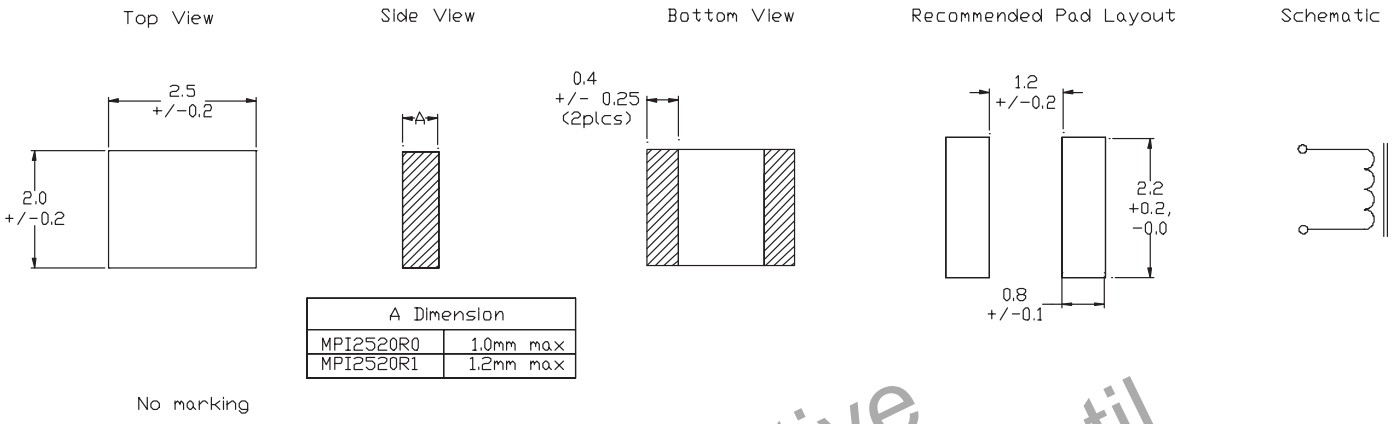
Powering Business Worldwide

Product specifications

Part Number[5]	OCL1 (µH)±20%	I_{rms}[2] (Amps)	I_{sat}[3] (Amps)	DCR (mΩ) @ 25°C typical	DCR (mΩ) @ 25°C max	K-Factor[4]
R0 —1.0mm Height						
MPI2520R0-R47-R	0.47	4.1	4.4	28	34	2887
MPI2520R0-1R0-R	0.9	3.2	3.2	50	60	1925
MPI2520R0-1R5-R	1.5	2.4	2.6	80	96	1444
MPI2520R0-2R2-R	2.2	2.2	2.4	103	124	1283
MPI2520R0-3R3-R	3.3	1.6	1.6	190	228	1050
MPI2520R0-4R7-R	4.7	1.4	1.4	240	288	825
R1 - 1.2mm Height						
MPI2520R1-R47-R	0.47	4.5	4.8	20	24	2310
MPI2520R1-1R0-R	1.0	3.7	4.0	35	42	1925
MPI2520R1-1R5-R	1.5	2.9	3.2	55	66	1444
MPI2520R1-2R2-R	2.2	2.3	2.7	75	90	1255
MPI2520R1-3R3-R	3.3	1.8	2.4	105	126	962
MPI2520R1-4R7-R	4.7	1.6	1.9	150	180	825
MPI2520R1-5R6-R	5.6	1.5	1.5	200	240	679
MPI2520R1-6R8-R	6.8	1.3	1.3	300	360	679
MPI2520R1-100-R	10.0	1.1	1.2	390	468	525

1. Open Circuit Inductance (OCL) Test Parameters: 1MHz, 0.1Vrms, 0.0Adc, 25°C
2. I_{rms}: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.
3. I_{sat}: Peak current for approximately 10% rolloff at +25°C.
4. K-factor: Used to determine B_{p-p} for core loss (see graph). $B_{p-p} = K * L * \Delta I / B_{p-p}$:(Gauss), K: (K-factor from table), L: (Inductance in µH), ΔI (Peak to peak ripple current in Amps).
5. Part Number Definition: MPI2520Rx-yyy-R
   - MPI2520Rx = Product code and size
   - yyy = Inductance value in µH, R = decimal point, if no R is present then third character = number of zeros.
   - "-R" suffix = RoHS compliant

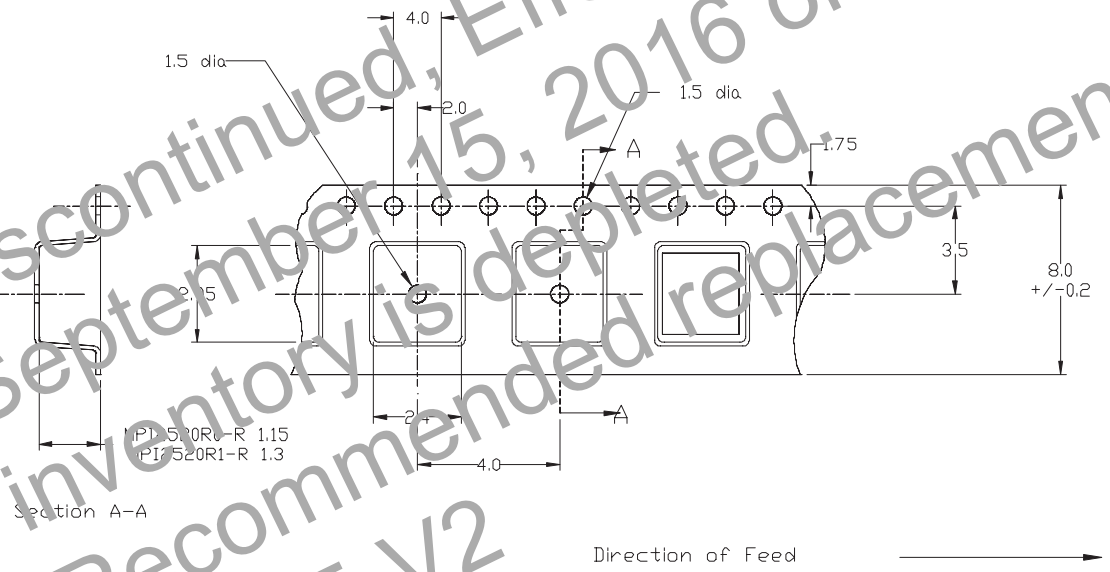
Dimensions - mm



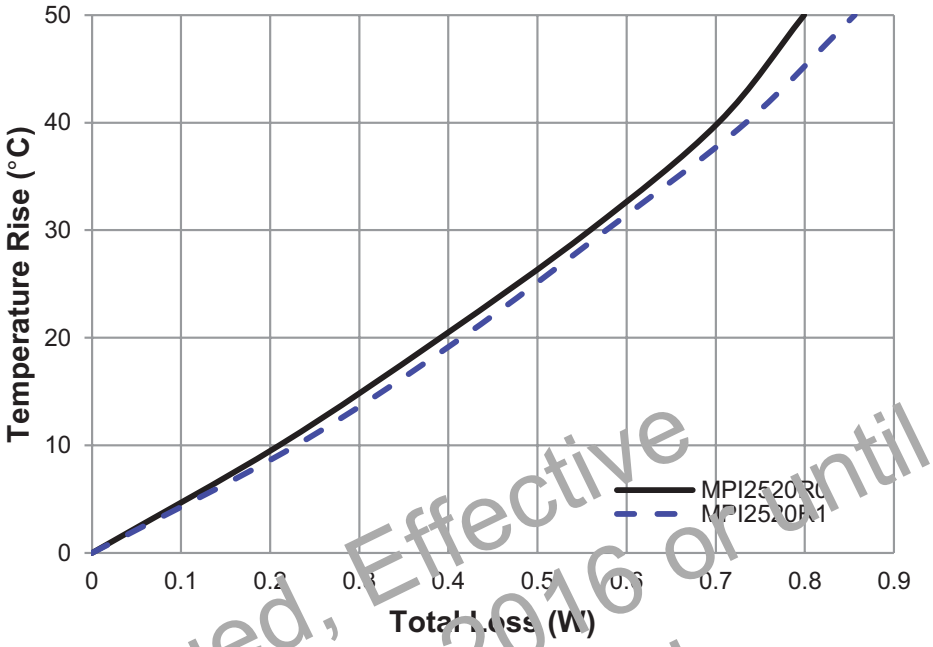
A Dimension	
MPI2520R0	1.0mm max
MPI2520R1	1.2mm max

No marking

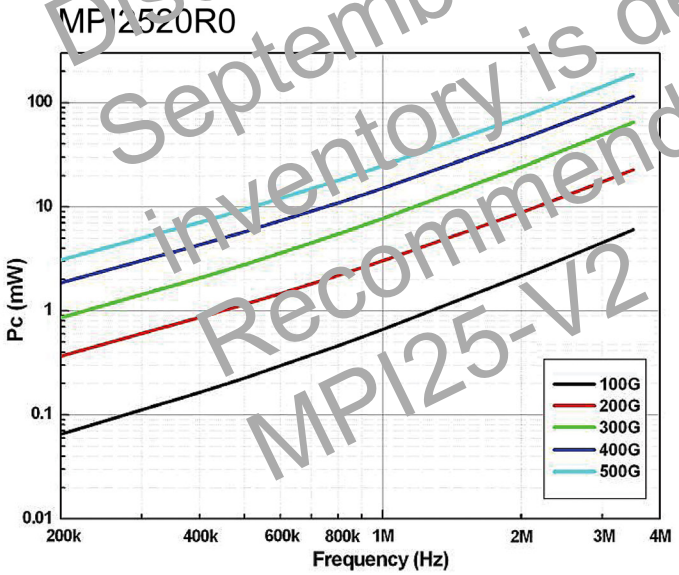
Packaging information - mm

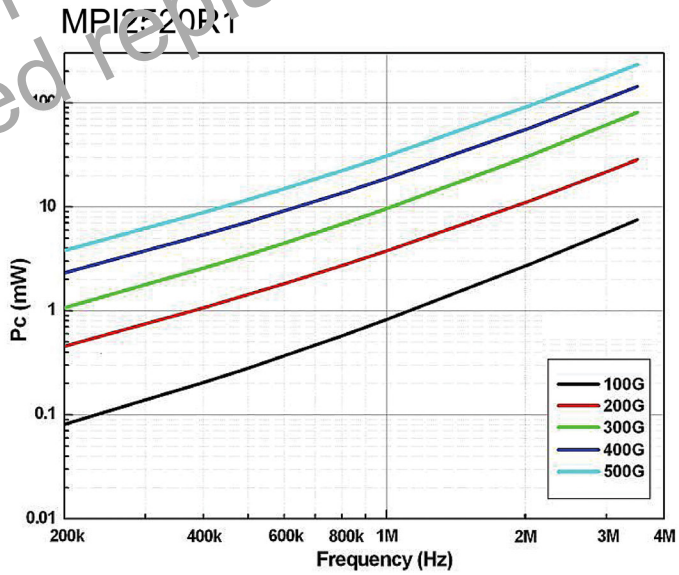


Temperature rise vs. total loss

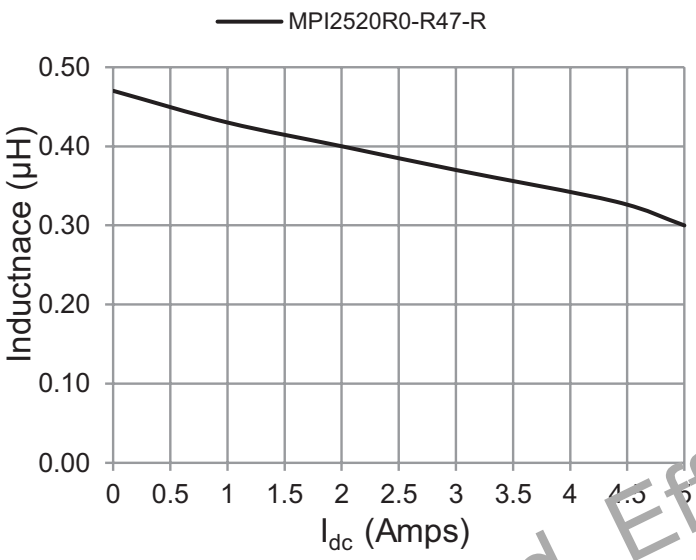


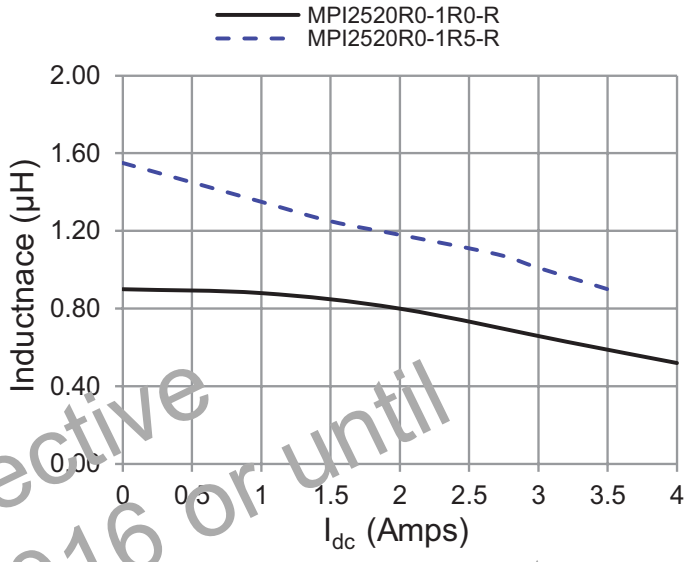
Core loss

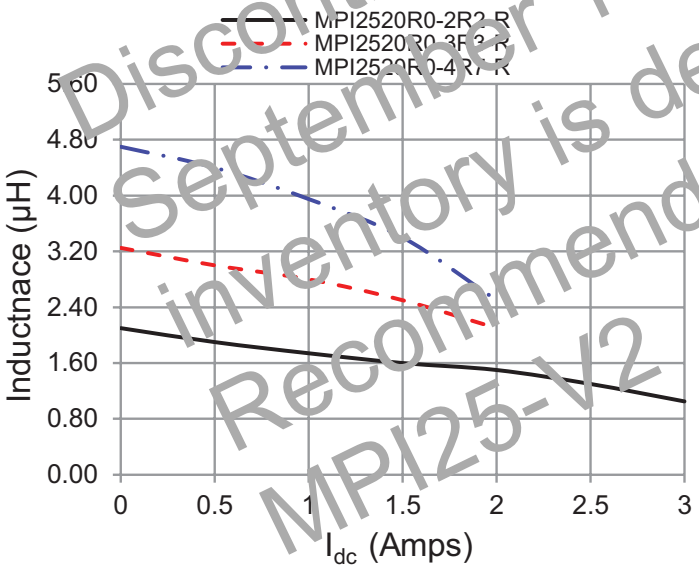


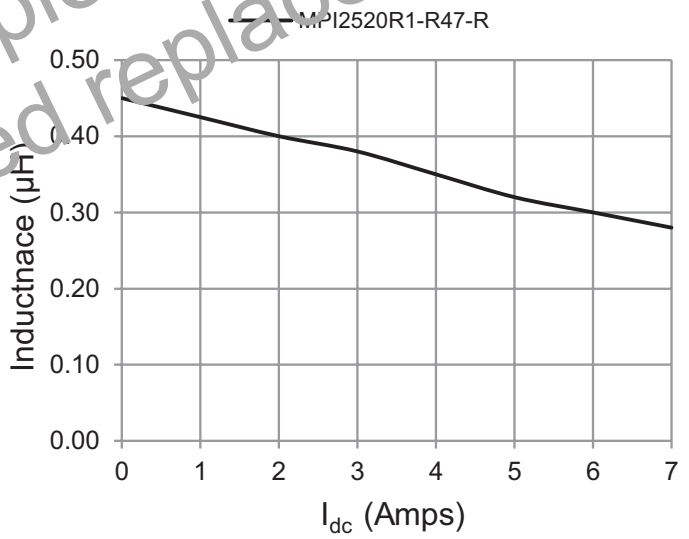


Inductance characteristics

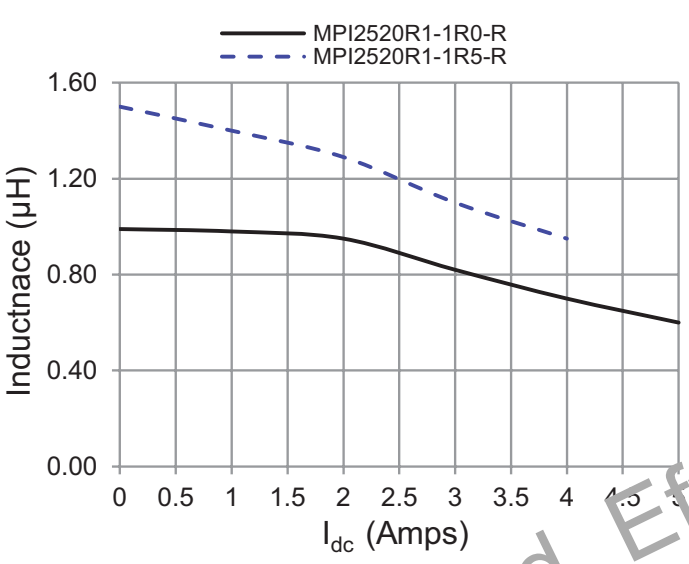


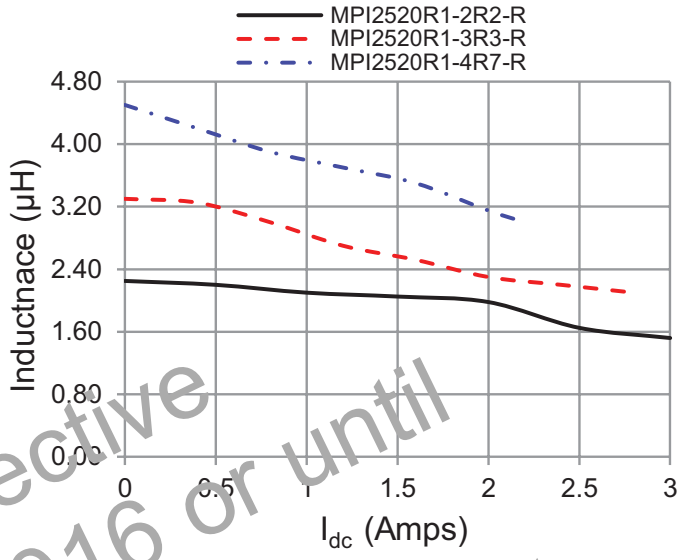


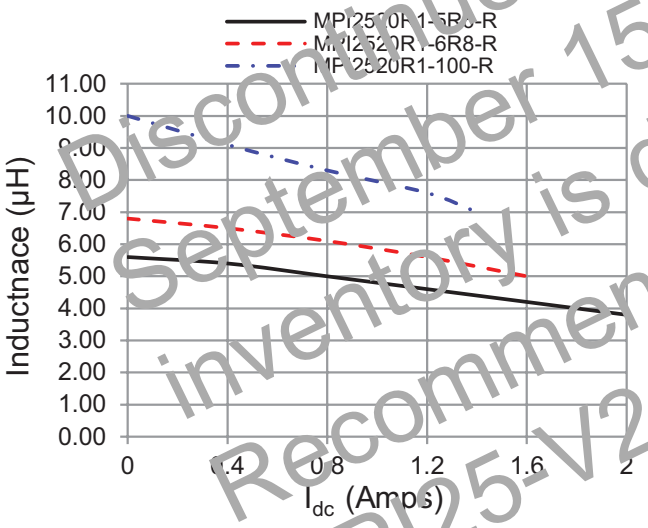




Inductance characteristics







Solder reflow profile

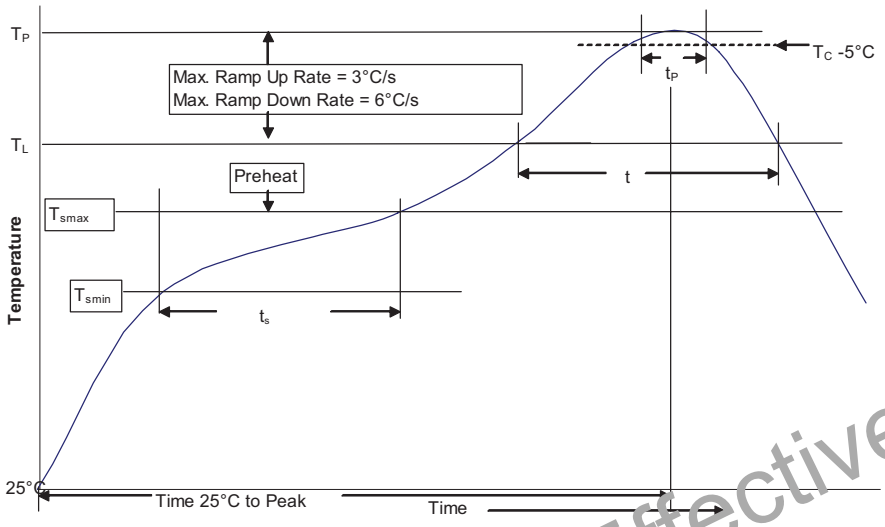


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm³ <350	Volume mm³ ≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature		Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak	• Temperature min. (T_{smin})	100°C	150°C
	• Temperature max. (T_{smax})	150°C	200°C
	• Time (T_{smin} to T_{smax}) (t_S)	60-120 Seconds	60-120 Seconds
Average ramp up rate (T_{smax} to T_p)		3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L)		183°C	217°C
Time at liquidous (t_L)		60-150 Seconds	60-150 Seconds
Peak package body temperature (T_P)*		Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_C)		20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})		6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature		6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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